

# SOT1021-1

plastic low profile fine-pitch ball grid array package; 324 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA324
<b>Package type industry code</b>	LFPGA324
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-8-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	16.9	-	17	17.1	mm
E	package width	16.9	-	17	17.1	mm
A	seated height	[tbd]	-	1.7	1.7	mm
A <sub>2</sub>	package height	1.15	-	1.35	1.35	mm
e	nominal pitch	-	-	0.8	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	324	-	



## 2. Package outline

LFBGA324: plastic low profile fine-pitch ball grid array package; 324 balls SOT1021-1

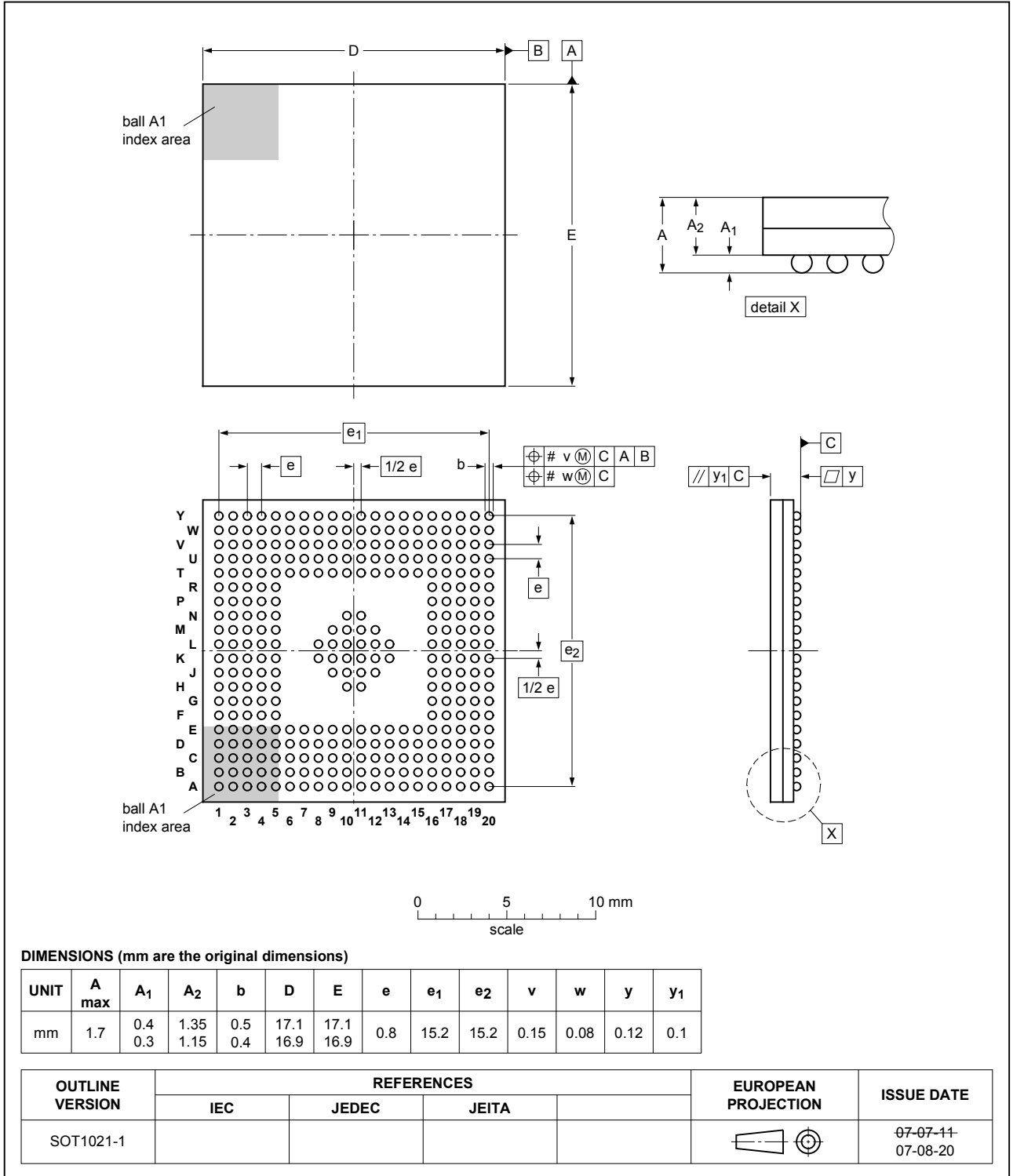


Fig. 1. Package outline LFBGA324 (SOT1021-1)

### 3. Legal information

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## 4. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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Date of release: 8 February 2016

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